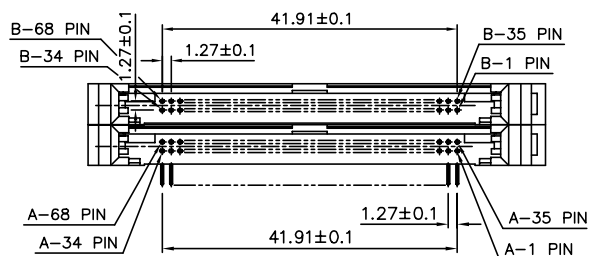
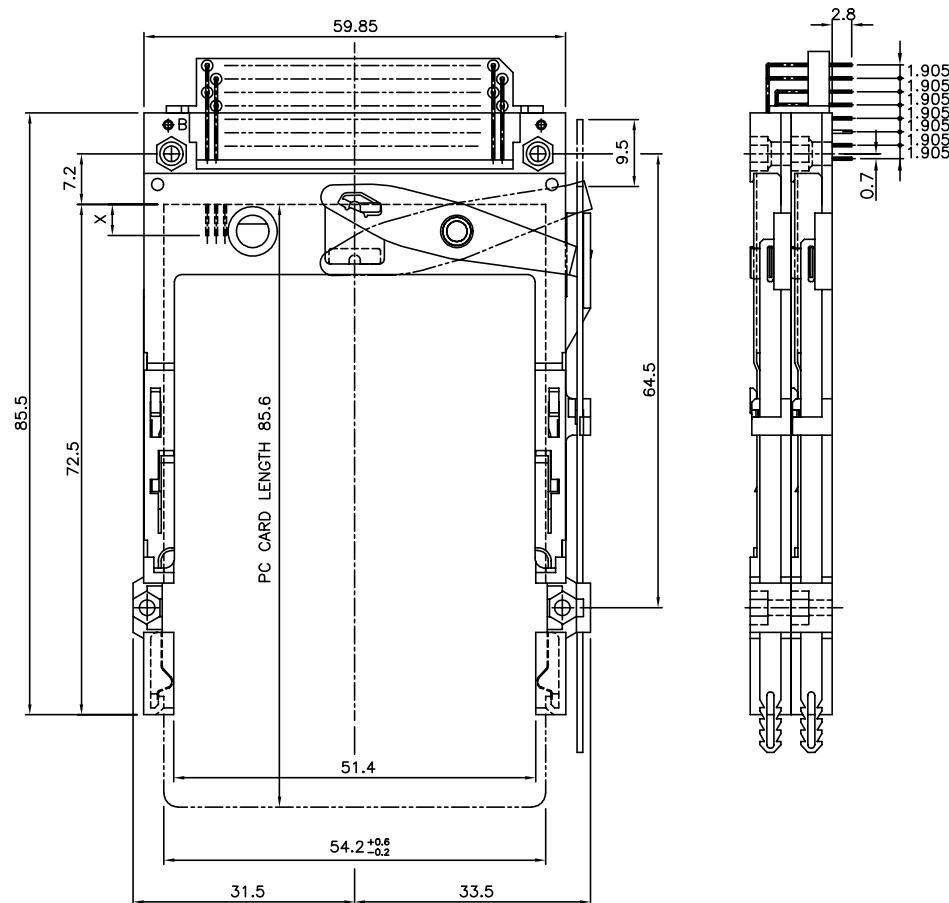


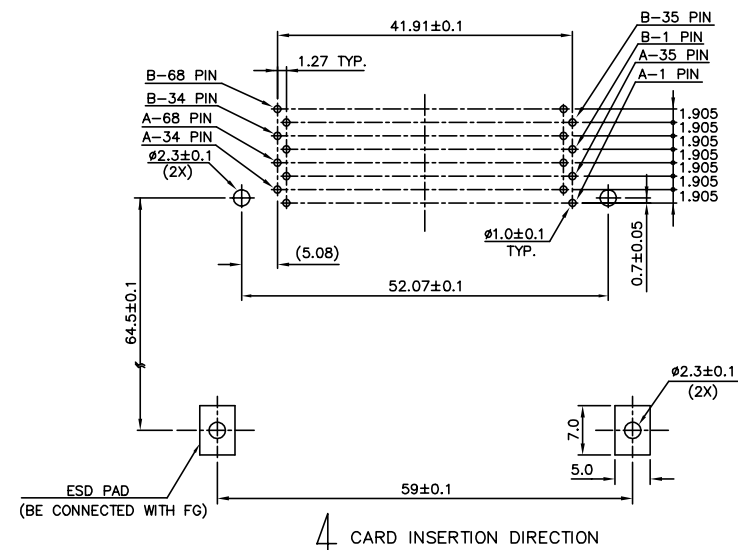
PRODUCT NO.	
57455-800CA	
57455-800CALF	



NOTES:

- EJECT FORCE : 3.5 Kg MAX.
- EJECT TRAVEL: 8.0mm
- MATERIAL:
 - HEADER ASS'Y :
 - PLASTIC : HOUSING ...HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
 - : LOCATOR ...HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
 - PIN : COPPER ALLOY
 - EJECT MECHANISM ASS'Y :
 - PLASTIC : GUIDE: HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
 - : PUSH ROD: HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
 - PLATE : STAINLESS
 - EMI CONTACT: PHOSPHOR BRONZE
- FINISH (PIN):
 - UNDER PLATING : 1.25 μ m MIN. Ni
 - CONTACT AREA : 0.076 μ m MIN. GOLD
 - SOLDER TAIL : 2.5 μ m MIN. Sn-Pb
 - : 2.5 μ m MIN. PURE Sn (FOR -*****LF)
- DIM "X"

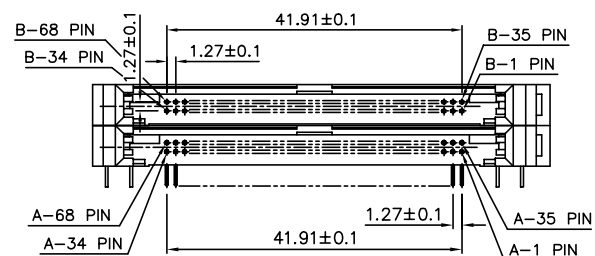
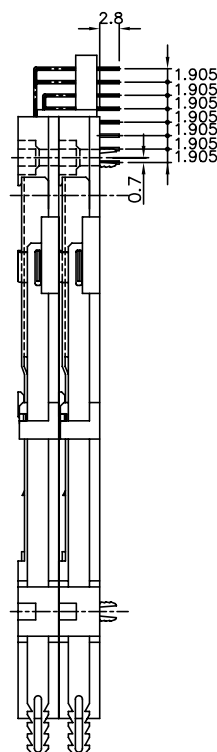
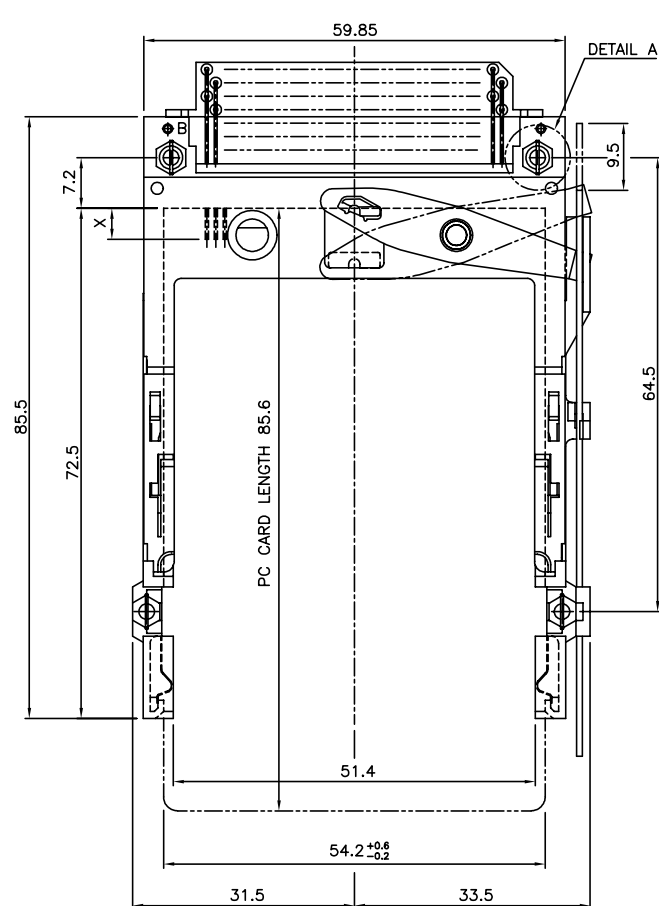
4.25±0.1	3.5±0.1	5.0±0.1
OTHERS	36,67	1,17,34,35,51,68
- IF LEAD FREE P/N THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
- IF LEAD FREE P/N THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
- LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
- PRODUCT SPEC: 110-263



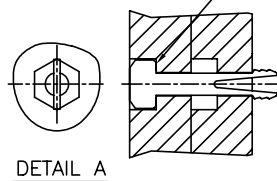
4 CARD INSERTION DIRECTION

mat'l. code				surface		tolerance		projection		product family	
ISO1302				ISO1101		ISO406		MM		PCMCIA	
tolerances unless otherwise specified				angle		±0.30		scale		R/A EJECTOR HDR ASS'Y	
T10220 WL 08/15/01				T20214 WL 07/01/02		N05-0155 WB 06/10/05		BX-N-011383 ZK 04/02/12		TYPE 1/2/3	
dr WENDY CHEN 05/30/01				eng MINERVA WANG 05/30/01		chr MINERVA WANG 05/30/01		appd JENN TSAO 05/30/01		dwg no 57455	
sheet index				revision D		D		type Product Customer Drawing		sheet 1 of 2	
1				2						A4	

PRODUCT NO.
57455-800CAH
57455-800CAHLF



NO PLAY BETWEEN
HOLD DOWN AND HEADER

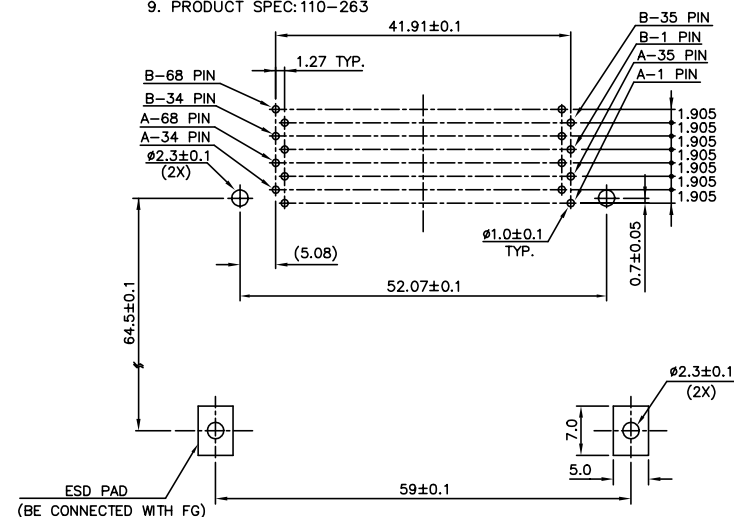


NOTES:

- EJECT FORCE : 3.5 Kg MAX.
- EJECT TRAVEL: 8.0mm
- MATERIAL
- HEADER ASS'Y :
PLASTIC : HOUSING ...HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
LOCATOR ...HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PIN : COPPER ALLOY
- EJECT MECHANISM ASS'Y :
PLASTIC : GUIDE: HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PUSH ROD: HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PLATE : STAINLESS
EMI CONTACT: PHOSPHOR BRONZE
- FINISH (PIN)
UNDER PLATING : 1.25 μ m MIN. Ni
CONTACT AREA : 0.076 μ m MIN. GOLD
SOLDER TAIL : 2.5 μ m MIN. Sn-Pb
SOLDER TAIL : 2.5 μ m MIN. PURE Sn (FOR -*****LF)

5. DIM "X"	4.25 $\pm$ 0.1	3.5 $\pm$ 0.1	5.0 $\pm$ 0.1
OTHERS	36,67	1,17,34,35,51,68	

- IF LEAD FREE P/N THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
- IF LEAD FREE P/N THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
- LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
- PRODUCT SPEC: 110-263



4 CARD INSERTION DIRECTION

mat'l. code	surface	tolerance	projection	product family
ISO1302	ISO1101	ISO406		PCMCIA
l'tecn nodr	date	tolerances unless otherwise specified		
D		angle	MM	R/A EJECTOR HDR ASS'Y
		0 $\pm$ 2'	scale	TYPE 1/2/3
dr	WENDY CHEN	05/30/01		dwg no
eng	MINERVA WANG	05/30/01		sheet 2 of 2
chr	MINERVA WANG	05/30/01		size
app	JENN TSAO	05/30/01		A4
sheet	revision			type
index	sheet			Product Customer Drawing